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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Sung-Fei WANG, et al

Serial No.: 10/087,432

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SUBSTITUTE DECLARATION

Sir:

Kindly substitute the attached Combined Declaration and Power of Attorney with the original ink signature for the document previously filed on March 1, 2002.

Respectfully submitted,

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CERTIFICATE OF MAILING (37 CFR 1.8a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Commissioner of Patents and Trademarks, Washington, DC 20231

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